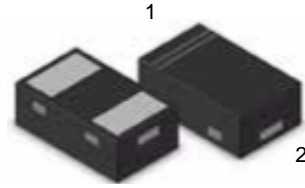
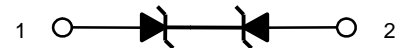


Features

- I 32 W (8/20μs) Peak Pulse Power
- I Low Capacitance ESD Protection
- I SOD-882 Package
- I RoHS Compliant
- I Matte Tin Lead finish (Pb-Free)
- I Protect One High Speed Data Line
- I Meet IEC61000-4-2 Level 4: Contact Discharge > 8kV , Air Discharge > 15kV



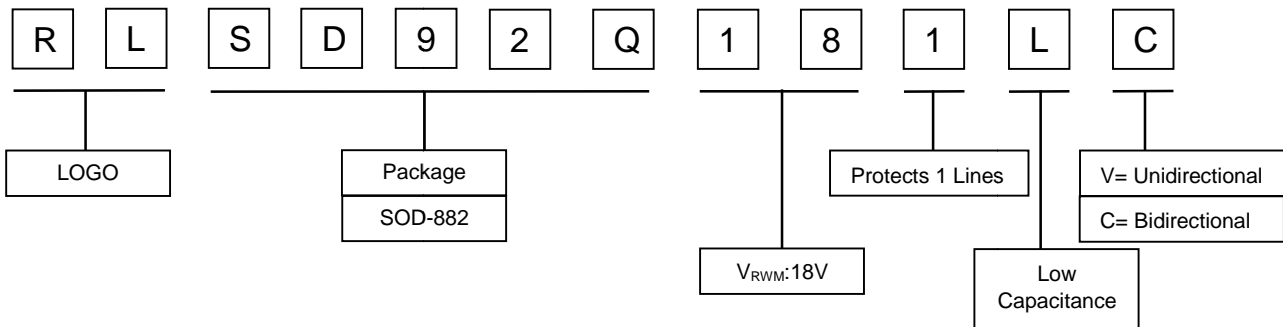
Electrical symbol



Applications

- I Communication System
- I Portable Instrumentation
- I Audio and Video Equipment
- I Computers and Peripherals
- I USB 2.0, USB 3.0 Ports

Part Number Code



Absolute Maximum Rating

Rating	Symbol	Value	Units
Peak Pulse Power (tp =8/20μs)	P _{PK}	32	W
ESD Voltage (Contact)	V _{ESD}	8	Kv
ESD Voltage (Air)	V _{ESD}	15	Kv
Operating Temperature	T _J	-55 to 150	°C
Storage Temperature	T _{STG}	-55 to 150	°C

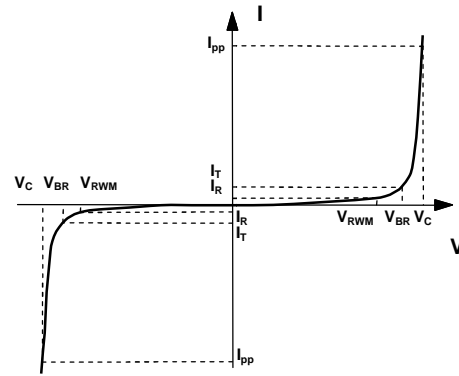
Electrical Characteristics (@ 25°C Unless Otherwise Specified)

Type Number	Reverse Stand-Off Voltage	Minimum Breakdown Voltage	Peak Pulse Voltage @8/20μS	Peak Pulse Current @8/20μS	Reverse Leakage @V _{RWM}	Typical Capacitance
	V _{RWM}	V _{BR} @1mA	V _C @1A	I _{PP}	I _R @(V _{RWM} =5V)	DC=0V C _J @ 1 MHz
	V	V	V	A	μA	pF
RLSD92Q181LC	18	18.5	27	1	0.1	0.25

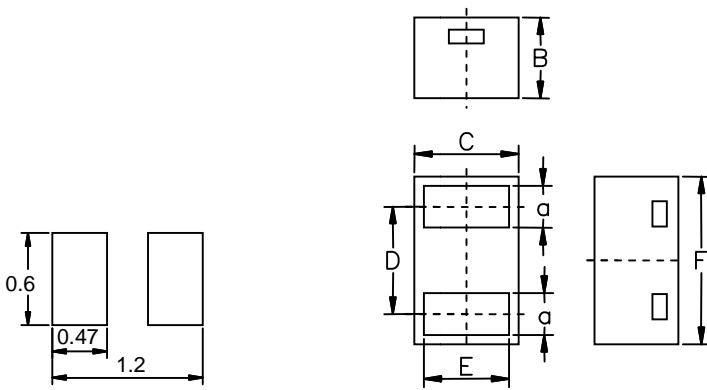


Electrical Parameters (T=25°C)

Symbol	Parameter
I_{PP}	Maximum Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Working Peak Reverse Voltage
I_R	Maximum Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current



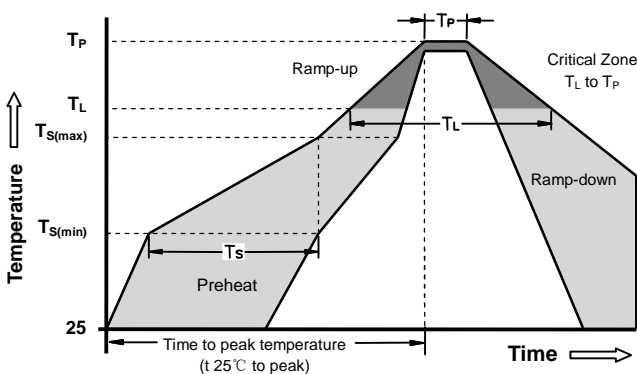
Dimensions & Recommended soldering footprint(mm)



DIM	Millimeters		Inches	
	Min	Max	Min	Max
B	0.34	0.44	0.013	0.017
C	0.60BSC		0.024BSC	
D	0.65BSC		0.026BSC	
E	0.43	0.53	0.017	0.021
F	1.00BSC		0.039	
a	0.20	0.30	0.008	0.012

Part Number	Component package	Quantity	Reel Size	Molding compound flammability rating	Lead Finish
RLSD92Q181LC	SOD-882	10000	7 inch	UL 94V-0	Lead Free

Soldering Parameters - Reflow Soldering (Surface Mount Devices)



Reflow Condition		Pb - Free assembly
Pre Heat	-Temperature Min ($T_{S(min)}$)	150°C
	-Temperature Max ($T_{S(max)}$)	200°C
	- Time (min to max) (t_s)	60 -180 Seconds
Average ramp up rate (Liquids Temp T_L) to peak		3°C/second max
$T_{S(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	- Temperature (T_L) (Liquids)	217°C
	- Time (min to max) (t_s)	60 -150 Seconds
Peak Temperature (T_P)		260 +0/-5°C
Time within 5°C of actual peak Temperature (t_p)		20 - 40 Seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_P)		8 minutes Max
Do not exceed		280°C

